

Half Tone Alternating Phase Shift Masks

Background of Invention

1) Field of the Invention

This invention relates generally to microelectronic masks and mask fabrication methods and more particularly to phase shift masks and fabrication methods thereof.

2) Description of the Prior Art

As integrated circuit devices such as semiconductor devices become more densely integrated, it may become increasingly difficult to form uniform patterns therein. This problem can be reduced or eliminated by using phase shift mask (PSM) structures rather than conventional photo mask structures. In particular, a Levenson PSM (or alternating PSM) may be used to form a uniform pattern. A Levenson PSM includes an etched portion in a PSM substrate. A Levenson PSM is described in detail in U.S. Pat. No. 5,358,827.

A conventional Levenson PSM is formed by sequentially forming a phase shift layer pattern and a chrome layer pattern which expose spaced apart regions of a PSM substrate. A trench having a predetermined depth is formed in one of the exposed regions. The phase of radiation such as light, which is incident on the region where the trench is formed is shifted by an angle of 180 degree. Thus, the region in which the trench is formed becomes a phase shift region. The phase of a light incident on the other exposed region is not shifted. Thus, the region in which a trench is not formed becomes an unshifted phase region.

1 Unfortunately, when the light passing through the phase shift region is
2 out of focus, the image of a pattern may deteriorate. Thus, the difference D of a critical
3 dimension (hereinafter, referred to as a CD) between patterns respectively formed by light
4 passing through the phase shift region and the unshifted phase region may become large. In
5 order to solve this problem, an undercut can be formed on the PSM substrate on which the
6 trench is formed, or a material having a high refractivity can be used to reduce the step
7 difference of the trench. However, these methods may not completely solve this problem.
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10 The importance of overcoming the various deficiencies noted above is
11 evidenced by the extensive technological development directed to the subject, as
12 documented by the relevant patent and technical literature. The closest and apparently
13 more relevant technical developments in the patent literature can be gleaned by considering
14 US 6,410,191B(Nistler et al.) that shows a single trench alternating PSM.

15 US 5,766,829(Cathey, Jr. et al.) shows a chromeless phase shift mask
16 comprised of a pattern of parallel spaced phase shifters.

17 US 6,458,495B1(Tsai, et al.) shows a dual trench with undercut, alt-
18 PSM.

19 US 6,355,399b1(Sajan et al.) shows a method for a dual damascene
20 pattern comprising: exposing a one photoresist layers using a grey tone mask.

21 US 6,482,554(Matsunuma) shows a method for a dual damascene
22 pattern comprising: exposing two photoresist layers using a grey (tri-tone) mask.
23

24 S. Vaidya, *Phase-Shifting Photomasks*, Semiconductor fabtech, Edition
25 1, Issued September 1994, S. Vaidya, AT&T Bell Laboratories, Murray Hill, New Jersey,
26 USA, Website:

27 <http://www.semiconductorfabtech.com/features/lithography/articles/body1.171.php3> ,
28 5/7/03

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2 John S. Petersen, et al., Development of a Sub-100nm Integrated
3 Imaging System Using Chromeless Phase-Shifting Imaging with Very High NA KrF
4 Exposure and Off-axis Illumination, found on website;
5 [http://www.advlitho.com/content/Papers/SPIE_microolith_02/4691-](http://www.advlitho.com/content/Papers/SPIE_microolith_02/4691-50_Petersen_Conley_et_al.pdf)
6 [50 Petersen Conley et al.pdf](http://www.advlitho.com/content/Papers/SPIE_microolith_02/4691-50_Petersen_Conley_et_al.pdf), May 8, 2003 , discusses Chromeless Phase shift mask
7 techniques.
8

9 Gerold, et al., *Multiple Pitch Transmission and Phase Analysis of Six*
10 *Types of Strong Phase-Shifting Masks*, This material was presented at SPIE's 26th Annual
11 International Symposium on Microlithography as presentation number 4346-72 , found on
12 website: <http://www.advlitho.com/content/Papers/4346-72paper.pdf> May 8, 2003. This
13 reference discusses alternating phase shift masks.
14

15 Armen Kroyan and Hua-yu Liu, *Effects of altPSM Design on Image*
16 *Imbalance for 65 nm*, *Semiconductor International*, 2/1/2003 [http://www.e-](http://www.e-insite.net/semiconductor/index.asp?layout=article&articleId=CA273367&spacedesc=webex)
17 [insite.net/semiconductor/index.asp?layout=article&articleId=CA273367&spacedesc=webex](http://www.e-insite.net/semiconductor/index.asp?layout=article&articleId=CA273367&spacedesc=webex)
18 x)

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3 **Summary of the Invention**

4 It is an object of embodiments of the present invention to provide a
5 structure and a method for fabricating an optical mask that overcome some of the
6 disadvantages of the Levenson phase shifting mask.

7 It is an object of embodiments of the present invention to provide a
8 structure and a method for fabricating a single trench- half tone phase shift mask.

9 It is an object of embodiments of the present invention to provide a
10 structure and a method for fabricating a dual trench- half tone phase shift mask.

11 Embodiments of the present invention provides a structure and method
12 of manufacturing a phase shift mask which is characterized below.

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14 An example embodiment of the invention comprises a structure for a
15 half tone alternating phase shift mask. The phase shift mask comprises the following:

16 a first phase shift section, a half tone section, and a second phase shift
17 section;

18 the first phase shift section adjacent to the half tone section;

19 the half tone section adjacent to the second phase shift section;

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21 the first phase shift section and half tone section changing the phase of
22 incident light by about 180 degrees with respect to the second phase shift section.

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25 A example embodiment of a method for forming a single trench half
26 tone alternating phase shift mask comprises the following:

- a) providing a substrate having a phase shift region, a half tone region and an unshifted phase region; the phase shift region adjacent to the half tone region; the half tone region adjacent to the unshifted phase region;
- b) forming a half tone layer on the substrate in the half tone region; the half tone layer has a phase shift of about 180 degrees with the unshifted phase region, the half tone layer has a transmittance between about 3 and 30%;
- c) forming a trench in the substrate in the phase shift region; the phase shift region has an about 180 degree phase shift with the unshifted phase region.
- d) forming a trench in the substrate in the phase shift region; the phase shift region has an about 180 degree phase shift with the unshifted phase region.

A example embodiment of a method for forming a single trench half tone alternating phase shift mask comprises the following:

- a) providing a mask substrate having a first phase shift region, a half tone region and an second phase shift region;
- b) the first phase shift region adjacent to the half tone region; the half tone region adjacent to the second phase shift region;
- c) forming a first trench in the substrate in the first phase shift region; the phase shift region has an about 180 degree phase shift with the unshifted phase region, the first phase shift region has about a 100 % transmittance;
- d) forming a half tone layer on the mask substrate in the half tone region; the half tone section has a phase shift of about 180 degrees with the

1 first phase shift region; the half tone layer has a transmittance between
2 about 0 and 100 % ;

- 3 e) forming a second trench in the substrate in the second phase shift
4 region; the second phase shift region has an about 180 degree phase
5 shift with the first phase shift region.
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8 An example embodiment for a method of fabricating a semiconductor
9 device comprises the following:

- 10 a) providing a phase shift mask comprising:

- 11 (1) a mask substrate having a first phase shift section, a half tone section
12 and a second phase section;
13 the first phase shift section adjacent to the half tone section;
14 the half tone section adjacent to the second phase section;
15 the first phase shift section and the half tone layer have about a 180
16 degree phase shift with the second phase section;
17 the half tone layer has a transmittance between about 0.1 and 98 %;

- 18 b) transmitting radiation through portions of the phase shift mask to expose
19 a pattern of photoresist overlying a semiconductor workpiece; and
20 c) utilizing the patterned photoresist to fabricate a semiconductor device.
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23 Additional objects and advantages of the invention will be set forth in
24 the description that follows, and in part will be obvious from the description, or may be
25 learned by practice of the invention. The objects and advantages of the invention may be
26 realized and obtained by means of instrumentalities and combinations particularly pointed
27 out in the append claims.

Brief Description of the Drawings

The features and advantages of an alternating PSM according to the present invention and further details of a process of fabricating and using such a mask in accordance with the present invention will be more clearly understood from the following description taken in conjunction with the accompanying drawings in which like reference numerals designate similar or corresponding elements, regions and portions and in which:

Figure 1A is a cross sectional view of a single trench half tone alternating phase shift mask according to an embodiment of the present invention.

Figure 1B is a top plan view of a single trench half tone alternating phase shift mask according to an embodiment of the present invention.

Figure 2 is a cross sectional view of a single trench half tone alternating phase shift mask and graph of E-field according to an embodiment of the present invention.

Figure 3A is a cross sectional view of a single trench half tone phase shift mask and E-field equations according to an embodiment of the present invention.

Figure 3B shows a Prolight intensity simulation showing Intensity vs displacement for a levenson mask and the embodiments' single trench half tone alt-PSM.

Figures 4A thru 4L are cross sectional views of a process to make a single trench half tone alternating phase shift mask according to an embodiment of the present invention.

Figure 5 is a cross sectional view of a dual trench half tone alternating phase shift mask according to an embodiment of the present invention.

Figure 6 is a cross sectional view of a dual trench half tone alternating phase shift mask and graph of E-field according to an embodiment of the present invention.

Figure 7 is a cross sectional view of a Levenson (alternating) PSM according to the prior art.

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Figures 8A to 8M are cross sectional views of a process to make a dual trench half tone alternating phase shift mask according to an embodiment of the present invention.

Figure 9 shows a mask 900 of an embodiment of the invention with radiation transmitted thru the mask onto a resist layer 910 over a work piece 920 according to an embodiment of the invention.

Detailed Description of the Preferred Embodiments

The embodiments of the present invention will be described in detail with reference to the accompanying drawings.

The embodiments provide a phase shift mask having a first phase shift section, a half tone section, and a second phase shift section. The embodiments' half tone section assists in balancing the intensity between light passing thru the first phase shift section and the second phase shift section.

Two mask embodiments comprise (1) a single trench half tone phase shift mask and (2) a dual trench half tone phase shift mask. Other embodiments include methods for making the masks and using the masks to make devices.

Figure 1 shows a first embodiment of an single trench, half tone, alternating phase shift mask.

Figure 5 shows a second embodiment of a dual trench, half tone, alternating phase shift mask. The half tone regions provide advantages over conventional phase shift masks.

Structure for Single trench Half tone alternating PSM (alt-PSM)

A first example embodiment of the invention is a single trench half tone alternating phase shift mask (alt-PSM).

A. a first phase shift section A, a half tone section B, and a second phase shift section C

Referring to Figure 1A, the mask 12 preferably comprises a first phase shift section A, a half tone section B, and a second phase shift section (or unshifted phase section) C. The first phase shift section A is adjacent to the half tone section. The half tone section B is adjacent to the second phase shift section. Preferably as shown in figure

1 1A, there is no opaque section in the half tone region between the first and second phase
2 shift sections A and C.

3
4 The first phase shift section and half tone section change the phase of
5 incident light 13 by about 180 degrees with respect to the second phase shift section (or
6 unshifted phase section) C. In this embodiment the first phase shift section comprises a
7 (first) phase shift region 20 of the mask substrate 10. The half tone section comprises a half
8 tone layer 34 over a half tone region 26 of the mask substrate. The second phase shift
9 section C comprises an unshifted phase region (or second phase shift region) 24 of the
10 mask substrate. The unshifted phase region preferably comprises a un-etched/un-thinned
11 substrate surface 35.

12 We provide a mask substrate 10. The substrate preferably has at least a
13 (first) phase shift region 20, a half tone region 26, an unshifted phase region (or second
14 phase shift region) 24 and an opaque region (See figure 4L (30)). Light entering the mask
15 and exiting the mask in these regions may have changed phase and intensity. The mask is
16 preferably for use with light at a wavelength preferably between 157 and 248 nm and more
17 preferably 157 nm, 193 nm or 248 nm. Preferably the mask is exposed using
18 Convention/Standard illumination with low parital coherency factor: between ~ 0.20 and
19 0.40 .

20 The phase shift region 20 is adjacent to the half tone region. The half
21 tone region is adjacent to the unshifted phase region 24.

22 The substrate is preferably mask substrate such as a mask blank
23 comprised of quartz.

24 Figure 1A shows incident light 13 entering the rear side of the mask 12
25 and transmitted light 14 exiting the mask.

1 **B. Phase Shift Region 20**

2 A trench 32 is in the substrate 10 in the phase shift region (20). The
3 phase shift region 20 has an about 180 degree phase shift with the unshifted phase region
4 (24). The trench has a first depth 33 such the light at the wavelength transmitted through
5 the phase shift region (20) is shifted in phase by about 180 degrees relative to the light at
6 the wavelength transmitted through the unshifted phase region (24). The phase shift
7 region (20) has about a 100 % transmittance.

8 **C. Half tone Region 26**

9 A half tone layer 34 (or partially transmitting phase shift layer) is over
10 the mask substrate 10 in the half tone region 26. The half tone region comprises the mask
11 substrate and the half tone layer) over the mask substrate in the area. Light transmitted
12 thru the half tone region 26 (B) is phase shifted about 180 degrees with respect to
13 transmitted light passing thru the unshifted phase region (24) . The half tone layer 34
14 phase shifts light an amount depending on the line and space width target to be imaged on
15 the wafer and the process.

16 The half tone layer preferably has a transmittance between about 3 and
17 30%.

18 Referring to figure 3A, transmitted light thru phase shift region A is
19 about 180 degrees out of phase with light transmitted thru unshifted region (24). Light
20 thru half tone region (26) is about in phase with transmitted light thru phase shift region
21 A.

22
23 The half tone layer can be comprised of one or more layers. For
24 example, the half tone layer be made of 2 layers with a first layer to reduce transmission
25 and 2nd layer to phase shift light. If the half tone layer is comprised of 2 or more layers,
26 the edges of the layers are preferably even.

1 **D. Unshifted (or second) phase region 24**

2 The unshifted phase region 24 preferably has a transmission of about
3 100 % and about a 0 degree phase shift with incoming light. That is, if light (e.g., incident
4 light 13) entering the mask 12 from the back side is at a 0 phase degrees, then light (e.g.,
5 transmitted light 14) passing out of the mask in the unshifted phase region 24 has a phase
6 shift of about 0 degrees.

7 In actual application, the phase of the light entering the mask with
8 respect to the unshifted phase region 24 is not important. The light entering can be in any
9 phase degree. The phase is important only when the light exits the mask (transmitted light).

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11 **E. Opaque region**

12 Referring to figure 4L, (region 30) an opaque layer 102B is formed
13 over the substrate 100. Preferably the opaque layer is formed on the at least the edges of
14 the mask. The opaque regions are also present on masks so that the machine (scanner
15 and/or stepper) can use the registration marks and labels pattern on it for alignment of the
16 mask to the wafer stage as well as reticle identification.

17
18 Figure 1B shows a top down view of the mask section shown in figure
19 1A.

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21 A summary of the characteristics of the single trench half tone
22 alternating phase shift mask is shown below in table 1.

1 **Table 1 : Characteristic of single trench half tone alternating phase shift mask.**

Region	phase shift of transmitted light (degrees)	transmittance (%)
phase shift region (20)	180 degrees range = 178 to 182 degrees	100 % range = 95 to 100 %
half tone region (26) and half tone layer	180 degree range = 178 to 182 degrees	preferred range = 3 to 30 % range = 0.1 to 98%
unshifted phase region (24)	0 degrees range = -2 to 2 degrees	range = 0 to 100 %
opaque region (30)	0 degrees	0 %

3 **F. E-field graph**

4 Figure 2 shows a graph of e-field strength for the various regions of the
5 single trench half tone alt-PSM 12. The single trench half tone alt-PSM 12 is shown in the
6 upper area of figure 2. The amplitude of E_B is dependent on the light transmission thru the
7 half tone material.

8 **G. phase shift and transmittance**

9 Figure 3A shows a cross section of the Single trench half tone alt-psm
10 and the equations for Electric field (E) for light passing thru the three regions of the mask :
11 A - phase shift section), B – half tone section, and C – unshifted section.

12 Where: E is Electric field
13 θ is phase
14 T is transmittance
15

16 The light entering the quartz substrate can be any phase. For simplicity,
17 let the phase angle be 0. The transmitted light leaving the mask at sections A and C is
18 about 180 degree out of phase. The light transmitted thru section B is about in phase with
19 the light transmitted thru section A.

H. Prolitho intensity simulation

Figure 3B shows a Prolitho intensity simulation for the embodiment's single trench half tone alternating PSM. The figure shows Two curves: (302) levenson PSM (opaque layer on substrate between openings) with no undercuts, and (300) the embodiment's single trench half tone alternating PSM. The masks have equal line width and space of $0.18\text{ }\mu\text{m}$ at $0.248\text{ }\mu\text{m}$ wavelength illumination.

Compared to the levenson PSM, the embodiment's single trench half tone alternating PSM (302) has more equal balance intensity thru the two openings.

For (300) the embodiment's single trench half tone alternating PSM, the lesser imbalance in intensity at the first opening/section (A) and second opening/section (C) regions can be seen. An advantage of the embodiment is that the transmission % of the half tone material 34 can be adjusted to increase the intensity at first phase shift section A. The transmission % of the half tone material can adjusted to determine the optimum intensity thru phase shift section A to balance with the intensity thru the other opening in section C.

Process for the Single Trench Half tone Alternating PSM

An embodiment of the method for forming a single trench half tone alternating phase shift mask for use with light at a wavelength is described below.

Referring to figure 4A, we provide a substrate having: a phase shift region (20), a half tone region (26) and an unshifted phase region (24) and an opaque region (30).

The phase shift region (20) is adjacent to half tone region. The half tone region is adjacent to an unshifted phase region (24).

The substrate is preferably a mask blank comprised of quartz.

Preferably the substrate has about a 100 % transmittance and about a 0 degree phase shift.

1 **A. *half tone layer 101 and opaque layer 102***

2 Referring to figure 4A, we form a half tone layer 101 over the substrate
3 100. The half tone layer 101 is preferably comprised of: molybdenum silicide,
4 molybdenum silicon oxide, silicon nitride, or silicon oxinitride.

5 Tuning the transmission of the half tone layer can corrected the
6 placement error of Levenson's PSM. This allows the embodiment mask to equalize the
7 intensity of the light thru the phase shift region and unshifted region. This compensates
8 for the intensity imbalance of a Levenson alt-PSM. Varying the thickness of the half tone
9 layer will change the transmission rate. By proper optimization of half tone transmission
10 and thickness, intensity imbalance can be compensated without any undercutting.

11 Next, we form an opaque layer 102 on the half tone layer 101. The
12 opaque layer 102 is preferably comprised of chrome.

13 **B. *pattern the opaque layer 102 on the half tone layer 101***

14 Still referring to figure 4A, we form a first resist layer 103 on the
15 opaque layer 102.

16 As shown in figure 4B, we expose and develop the resist layer to
17 remove portions of the first resist layer to form a first resist pattern 103A over the half tone
18 region 26 and the opaque region 30. The first resist pattern preferably has first resist layer
19 openings 110 over the phase shift region (20) and an unshifted phase region (24).
20 The first resist layer can be negative or positive type photoresist.

21 Referring to figure 4C, we pattern the opaque layer 102 and half tone
22 layer 101 using the first resist pattern 103A as a mask to form a first opaque layer/half
23 tone layer pattern 102A 101A over the half tone region 26 and form a first openings 114
24 (in the opaque pattern and half tone pattern) to expose the substrate 100 in the phase shift
25 region (20) and an unshifted phase region (24).

26 The patterning the opaque layer 102 on the half tone layer 101 is
27 preferably performed using a reactive ion etch.

1 Referring to figure 4D, we remove the first resist layer 103.

2 **C. form a trench 32 in the phase shift region 20**

3 As shown in figure 4E, we form a second resist layer 104 over the
4 opaque layer 102 on the half tone layer 101 and the substrate 100.

5 As shown in figure 4F, we expose and develop the second resist layer to
6 remove portions of the second resist layer 104 to form a second resist pattern 104A over
7 the unshifted region 24 and the opaque region 30. The second resist pattern 104A has
8 second resist layer openings 120 over the phase shift region 20.

9 As displayed in figure 4G, we form a trench 32 in the phase shift region
10 20. The trench preferably has a depth 33 so that the phase shift region 20 has a phase shift
11 of about 180 degrees with respect to light transmitted through the unshifted phase region.
12 The trench can be etch. The trench can have straight or rounded sidewalls. The bottom of
13 the trench can be flat or rounded. An advantage of the embodiment is that the trench can
14 have flat sidewalls and bottom and the trench does not have to be undercut. This reduces
15 manufacturing costs.

16 Referring to figure 4H, we remove the second resist pattern 104A.

17 **D. Remove the first opaque layer pattern 102A from over the**
18 **half tone region**

19 As shown in figure 4I, we form a third resist layer 105 over the
20 substrate.

21 As shown in figure 4J, we remove portions of the third resist layer 105
22 to form a third resist layer pattern 105A over the opaque region 30 and to form third resist
23 layer openings 124 to expose the phase shift region (20), the half tone region 26 and an
24 unshifted phase region (24).

25 As shown in figure 4K, we remove the opaque layer 102 from over the
26 half tone region layer 101 in the half tone regions 26 to leave half tone patterns 102B.

1 Also, the half tone patterns 101A can be etched backed to obtain the
2 desired transmission. The optimized transmission of the half tone material can be varied by
3 controlling the etch removal rate.

4 Referring to figure 4L, we remove the third resist layer 105. Figure 4L
5 shows an opaque section D which is comprised of a opaque region 30 of the substrate and
6 the opaque layer 102B. Preferably the unshifted section is comprised of the un-etched or
7 un-thinned mask substrate.
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2 **Second embodiment - a dual trench half tone alternating phase shift mask**

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4 As shown in Figure 5, a second embodiment comprises a dual trench
5 half tone phase shift mask 200. The mask 200 comprises a first phase shift section R, a
6 half tone section S, and a second phase shift section T.

7 The first phase shift section adjacent to the half tone section. The half
8 tone section is adjacent to the second phase shift section. The first phase shift section R
9 and half tone section S change the phase of incident light by about 180 degrees with
10 respect to the second phase shift section T.

11 The first phase shift section is comprised of (i) a first phase shift region
12 220 of a mask substrate 204 and (ii) a first trench 232 in the first phase shift region. The
13 half tone section S is preferably comprised of a half tone region 226 of the mask substrate
14 and a half tone layer 234 over the half tone region. The second phase shift section T is
15 preferably comprised of (a) a second phase shift region 222 of the mask substrate and (b) a
16 second trench 236 in the second phase shift region. The second phase shift section
17 preferably has about a 90 degree phase shift of incident light.

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19 The substrate 204 has at least a first phase shift region 220, a half tone
20 region 226 and an second phase shift region 222.

21 The first phase shift region 220 is adjacent to the half tone region 226.

22 The half tone region 226 is adjacent to the second phase shift region
23 222.

24 The first phase shift section and half tone section preferably shift
25 transmitted light about 270 degrees phase with respect to transmitted light thru the
26 (unshifted and unetched) quartz substrate surface.

1 The half tone section (S) has a phase shift of about 270 degrees with the
2 light at the wavelength with respect to transmitted light thru the (unshifted and unetched)
3 quartz substrate surface. The half tone layer has a transmittance between about 0.1 and 98
4 % and more preferably between about 3 and 30%.

5 The second phase shift section (T) has about a 90 degree phase shift
6 with respect to light transmitted thru the substrate (non-etched and non-shifted).
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9 **A. *first phase shift region 220***

10 A first trench 232 in the substrate in the first phase shift region 220. The
11 first trench has a depth such that the light at the wavelength transmitted through the first
12 phase shift region (220) is shifted in phase by 180 degrees relative to the light at the
13 wavelength transmitted thru the mask substrate. The first phase shift region 220 has
14 about a 100 % transmittance.

15 **B. *half tone layer 234***

16 A half tone layer 234 (partially transmitting phase shift layer) is over
17 the mask substrate 10 in the half tone region 226. The half tone region has a phase shift of
18 about 270 degrees with the light at the wavelength transmitted thru the mask substrate. The
19 half tone layer has a transmittance between about 0 and 100 % and more preferably
20 between 1 and 98 % and more preferably between about 3 and 30% .

21 **C. *second phase shift region 222***

22 The second phase shift region 222 has an about 180 degree phase shift
23 with respect to light thru the first shifted phase region (220) and the half tone region 226.

24 A second trench 236 is in the substrate in the second phase shift region
25 222. The trench has a depth 237 such that light that at the wavelength transmitted through

through the second phase shift region (222) is shifted in phase by 90 degrees relative light transmitted thru the substrate.

The second trench 236 has a depth such that light that at the wavelength transmitted through the second phase shift region (222) is shifted in phase by 180 degrees relative light transmitted thru the first phase shift region 220.

The second phase shift region 222 has about a 100 % transmittance.

Light thru the 1st phase shift region 220 is about 180 degree out of phase with light transmitted thru the half tone region/layer 226 234 and the 2nd phase shift region 222. Light thru half tone region 226 and half tone layer 234 is about in phase with transmitted light thru the second phase shift region 222.

Table 2 : Characteristic of dual trench half tone alt-phase shift mask.

Region	phase shift relative light transmitted thru the (unshifted) mask substrate (degrees)	transmittance (%)
first phase shift section (R)	270 range = 268 to 282	100 range = 95 to 100
half tone section (S)	270 degrees range = 268 to 272 degrees	range = 3 to 30 % range = 0.1 to 98%
second phase shift section (T)	90 degrees range = 88 to 92	range = 95 to 100 %
opaque section (U)	0	0

1 **D. *E field graph***

2 Figure 6 is a cross sectional view of a dual trench half tone phase shift
3 mask and graph of E-field at the mask surface according to an embodiment of the present
4 invention. The amplitude of E_s is dependent on the light transmission thru the half tone
5 material in region S.

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2 **Method for forming the dual trench Half tone alternating PSM**

3 An embodiment of the method for forming a (dual trench) half tone
4 alternating phase shift mask is described below.

5 **A. Mask Substrate**

6 Referring to figure 8A, we provide a mask substrate 800 having: a first
7 phase shift region (220), a half tone region 226 and a second shifted phase region (222)
8 and an opaque region 240.

9 The first phase shift region (220) is adjacent to half tone region (226).
10 The half tone region is adjacent to an second shifted phase region (222).

11 The substrate is preferably a mask blank comprised of quartz.
12 Preferably the substrate has about a 100 % transmittance and about a 0 phase shift.

13 **B. half tone layer 801 and opaque layer 802**

14 Referring to figure 8A, we form a half tone layer 801 over the substrate
15 800. The half tone layer 801 is preferably comprised of: molybdenum silicide,
16 molybdenum silicon oxide, silicon nitride, or silicon oxinitride.

17 Tuning the transmission of the half tone layer can correct the placement
18 error of Levenson's PSM, thus compensate intensity imbalance of Levenson PSM between
19 the phase shifted and unshifted regions. Varying the thickness of the half tone layer will
20 change the transmission rate. By proper optimization of half tone transmission and
21 thickness, intensity imbalance can be compensated without any trench undercutting.

22

23 Next, we form an opaque layer 802 on the half tone layer 801. The
24 opaque layer 802 is preferably comprised of chrome.

1 **C. **pattern the opaque layer 802 on the half tone layer 801***

2 Still referring to figure 8A, we form a first resist layer 803 on the
3 opaque layer 802.

4 As shown in figure 8B, we expose and develop the first resist layer to
5 remove portions of the first resist layer to form a first resist pattern 803A over the half tone
6 region 226 and the opaque region 240. The first resist pattern preferably has first resist
7 layer openings 810 over the first phase shift region (220) and an second phase region
8 (222). The first resist layer can be negative or positive type photoresist.

9 Referring to figure 8C, we pattern the opaque layer 802 and half tone
10 layer 801 using the first resist pattern 803A as a mask to form a first opaque layer/half
11 tone layer pattern 802A 801A over the half tone region 26 and form first openings 814
12 (in the opaque layer and half tone layer) to expose the substrate 800 in the first phase shift
13 region (220) and an second phase region (222).

14 The patterning of the opaque layer 802 on the half tone layer 801 is
15 preferably performed using a reactive ion etch.

16 **D. *form trenches 231 and 236***

17 Partial first trenches 231 are etched in the first phase shift regions 220
18 and second trenches 236 are etched in the substrate 800 in the second phase shift region
19 222.

20 The second trenches 236 are preferably etched to a depth to produce a
21 phase shift of 180 degree relative to the light transmitted thru the (not yet formed) first
22 trenches 220 (see figure 5). Preferably the second trench is etched to a depth 337 that phase
23 shifts light about 90 degree relative to the unetched (full thickness) substrate.

24 Referring to figure 8E, we remove the first resist layer 180.
25
26

1 **E. *form a second resist layer 804***

2 As shown in figure 8F, we form a second resist layer 804 over the
3 opaque layer 802 on the half tone layer 801 and the substrate 800.

4 **F. *form a second resist pattern 802A***

5 As shown in figure 8G, we remove portions of the second resist layer
6 804 to form a second resist pattern 802A over the second phase shift region 222 and the
7 opaque region 240. Also, we form second resist layer openings 820 over the first phase
8 shift region 220.

9 **G. *form a first trench 232 in the first phase shift region 220***

10 Referring to figure 8H, we form a first trench 232 in the first phase shift
11 region 220. The first trench 232 has a depth 233 so that the first phase shift region 220
12 has a phase shift of about 180 degrees relative to the second phase shift region 222 (second
13 trench 236). Preferably the first trench is etched to a depth that phase shifts light about 270
14 degree relative to the unetched (full thickness) substrate.

15 As shown in figure 8I, we remove the second resist pattern 804A.

16 **H. *third resist pattern 805A***

17 As shown in figure 8J, we form a third resist layer 805 over the
18 substrate.

19 As shown in figure 8K we removing portions of the third resist layer
20 105 to form a third resist pattern 805A over the opaque region 240 and to form a third
21 resist layer openings 828 to expose the half tone pattern 801A in the first phase shift
22 regions 220, and the half tone region 226 and an second phase shift region (222).

1 ***I. remove the opaque patterns 102A from over the half tone***
2 ***pattern 801A in the half tone regions 226***

3 As shown in figure 8L, we remove the opaque patterns 102A from over
4 the half tone pattern 801A in the half tone regions 226. The opaque patterns 102A can be
5 removed by either wet or dry etching.

6 The half tone patterns 810A can be etched backed to obtain the desired
7 transmission. The optimized transmission of the half tone material can be varied by
8 controlling the etch removal rate.

9 The transmission of the half tone patterns 810A can be optimized by
10 etching (or thinning) the half tone patterns 810.

11 As shown in figure 8M, we remove the third resist pattern 105A.
12 Figure 8M shows an opaque section U that comprises the opaque layer 802a over an
13 opaque region 240 of the mask substrate.
14

15 **Methods of making devices using the mask embodiments**

16 Embodiments include methods for making devices using the mask
17 embodiments.

18 The method preferably comprises: (a) providing a phase shift mask
19 comprising: a mask substrate having a first phase shift section, a half tone section and a
20 second phase section. The first phase shift section adjacent to the half tone section. The
21 half tone section adjacent to the second phase section. The first phase shift section and the
22 half tone layer have about a 180 degree phase shift with the second phase section. The
23 half tone layer has a transmittance between about 0.1 and 98 %.

24 Then we (b) transmit radiation through portions of the phase shift mask
25 to expose a pattern of photoresist overlying a semiconductor or electronic work piece.

26 Lastly, we (c) utilize the patterned photoresist to fabricate a
27 semiconductor device.

Figure 9 shows a mask 900 of an embodiment of the invention with light transmitted thru the mask onto a resist layer 910 over a work piece.

Advantages

Embodiments of the invention use a half tone layer and trenches preferably without trench undercut on the mask. The transmission rate of the half tone layer can range from >0.1 to $<100\%$, and more preferably from about 3% to 30%, depending on the need of the mask process and wafer process to achieve intensity balance for 0 and 180 degree as in the case of single trench half tone alt-PSM type, and for 90 and 270 degree as in the case of dual trench half tone alt-PSM type.

Tuning the transmission of the half tone layer can corrected the placement error of Levenson's PSM, thus compensate intensity imbalance of Levenson PSM. Varying the thickness of the half tone layer will change the transmission rate. By proper optimization of half tone transmission and thickness, intensity imbalance can be compensated without any undercutting.

Improvements over Levenson's PSM

Problems with undercutting trenches in Levenson's PSM

The inventors have found that the intensity imbalance on Levenson phase shifting mask (PSM) causes the placement error of the pattern feature during the photolithography process. Single (0/180 degree) and dual (90/270 degree) trench alt-PSM employs undercutting of the quartz in order to correct the intensity imbalance. However, the problem of undercuts is the high probability of the chrome been lifted off during mask manufacturing or cleaning process as the adhesive area of the chrome to the quartz is reduced. Chrome lifting limits the amount of undercuts to correct the intensity imbalance and features to go smaller as higher risk of chrome lifting due to right amount of undercut needed. Thus greatly reduce the application of Levenson PSM.

1 **Problems with interference at the air to quartz boundary surface in Levenson PSM's**

2 In Levenson's PSM shown in Fig. 7, the interference at the air to quartz
3 boundary surface (shown in region G) lowers the intensity between the etched region E and
4 the unetched region F. The imbalance in the intensity caused the patterned resist line on
5 the wafer to appear displaced towards the region of lower intensity. That is the intensity of
6 light E_E is less than the intensity of light E_F

7
8
9 The embodiments of the invention has half tone material on the unetch
10 regions, not opaque. The half tone material allows lights to pass through it while
11 maintaining the phase shift of the light, thus enabling the intensity to increase in the etched
12 region with the same phase. Although the amplitude of the etched region will not match
13 totally with the unetched region using this method, the increase in intensity level at the
14 threshold level which is needed to exposure the resist is matched. In this way, the
15 patterned line will not appear to be displaced.

16
17 As the intensity at the etched region that is needed to be balance with
18 the intensity at the unetched region is dependent on the transmission of the the half tone
19 material, detetmining the transmission level is cruical. Optimization of to the design CD
20 and space is needed with the transmission level is needed. This is achieved by measuring
21 the CD of the space produce by the etch and unetched region through simulation or
22 experimental result from patterened line with varying half tone material transmission.
23 From the simulation result, if both CDs of the spacing is the same, the intensity is balance,
24 else the difference in the CD will cause the line to appeared shifted. Experimental result
25 will yeild the same result, however it is more rigous. The transmission of the half tone
26 material can be varied by tuning the thickness while the phase can be tuned by the material
27 used.

1 The half tone alternating PSM masks of the invention may be used in
2 other types of PSMs. Also, subtractive alternating PSM methods are illustrated, but
3 additive half tone alternative PSM mask may be fabricated using the invention. Also, the
4 embodiments of the PSM eliminated the need for slope sidewalls trenches, but it may be
5 advantageous to form sloped sidewall trenches in the embodiment's half tone single and
6 dual trench alt-PSM.

7 The half tone alt-PSM's of the invention can be used to expose
8 photoresist in the manufacture of semiconductor, electronics and other devices. The
9 embodiments are suitable for defining conductive lines and patterns in resist for
10 semiconductor devices.

11 The above-described embodiments are meant to be illustrative of the
12 invention and not limiting. Modifications, alternatives, and variances to these embodiments
13 may be apparent to those skilled in the art. For example, although the above description
14 refers to a 0 degree and 180 degree phase, the present invention is equally applicable to
15 other embodiments in which the regions have different phases. In those embodiments, the
16 relative phase between the regions is approximately 180 degrees. Thus, the 0 degree phase
17 for a region and the 180 degree phase for another region, although providing one specific
18 embodiment, also indicate the phases for these two regions relative to one another.

19 In the above description numerous specific details are set forth in order
20 to provide a more thorough understanding of the present invention. It will be obvious,
21 however, to one skilled in the art that the present invention may be practiced without these
22 details. In other instances, well known process have not been described in detail in order
23 to not unnecessarily obscure the present invention.

24
25 While the invention has been particularly shown and described with
26 reference to the preferred embodiments thereof, it will be understood by those skilled in
27 the art that various changes in form and details may be made without departing from the
28 spirit and scope of the invention. It is intended to cover various modifications and similar

1 arrangements and procedures, and the scope of the appended claims therefore should be
2 accorded the broadest interpretation so as to encompass all such modifications and similar
3 arrangements and procedures.
4

What is claimed is :

1. A phase shift mask for use with light at a wavelength comprising:
 - a first phase shift section, a half tone section, and a second phase shift section;
 - said first phase shift section adjacent to said half tone section;
 - said half tone section adjacent to said second phase shift section;

said first phase shift section and half tone section changing the phase of transmitted light by about 180 degrees with respect to said second phase shift section.
2. The phase shift mask of claim 1 which further includes
 - said first phase shift section comprised of a first phase shift region of a mask substrate;
 - a trench in said first phase shift region; and
 - said half tone section comprised of (i) a half tone region of said mask substrate and (ii) a half tone layer over said half tone region;
 - said second phase shift section has about a 0 degree phase shift.
3. The phase shift mask of claim 1 which further includes:
 - said first phase shift section comprised of (i) a first phase shift region of a mask substrate and (ii) a first trench in said first phase shift region;
 - said half tone section comprised of a half tone region of said mask substrate and a half tone layer over said half tone region; said half tone layer has a transmittance between about 3 and 30%; and
 - said second phase shift section has about a 0 degree phase shift.

4. The phase shift mask of claim 1 which further includes:
 - said first phase shift section comprised of (i) a first phase shift region of a mask substrate and (ii) a first trench in said first phase shift region; and
 - said half tone section comprised of a half tone region of said mask substrate and a half tone layer over said half tone region;
 - said half tone layer has a transmittance between about 3 and 30%;
 - said second phase shift section comprised of (a) a second phase shift region of said mask substrate and (b) a second trench in said second phase shift region;
 - said second phase shift section has about a 90 degree phase shift.
5. The phase shift mask of claim 1 wherein said second phase shift region has about a 100 % transmittance.
6. The phase shift mask of claim 1 wherein said half tone section has a transmittance that balances the light intensities transmitted through said first phase shift region and said second phase shift region so that the light intensities are about equal.
7. A semiconductor device or an electronics device formed by using the phase shift mask of claim 1.
8. A phase shift mask for use with light at a wavelength comprising:
 - a mask substrate having a first phase shift region, a half tone region, and a second phase shift region;
 - said first phase shift region adjacent to said half tone region;
 - said half tone region adjacent to said second phase shift region;
 - a half tone layer over said half tone region;
 - said first phase shift region and half tone layer changing the phase of transmitted light by about 180 degrees with respect to said second phase shift region.

9. The phase shift mask of claim 8 which further includes a trench in said mask substrate in said first phase shift region; and
said second phase shift region has about a 0 degree phase shift; and
said half tone region has a transmittance between about 0.1 and 98 %.
10. The phase shift mask of claim 8 which further includes a trench in said mask substrate in said second phase shift region; and
said first phase shift region has about a 0 degree phase shift;
said half tone layer has a transmittance between about 3 and 30%.
11. The phase shift mask of claim 8 which further includes:
a first trench in said first phase shift region; and
a second trench in said second phase shift region; and
said half tone layer has a transmittance between about 3 and 30%.
12. The phase shift mask of claim 8 wherein said half tone layer has a transmittance between about 3 and 30% .
13. The phase shift mask of claim 8 wherein said second phase shift region has about a 100 % transmittance.
14. The phase shift mask of claim 8 wherein said half tone layer has a transmittance that balances the light intensities transmitted through said first phase shift region and said second phase shift region so that the light intensities are about equal.
15. A semiconductor device or an electronics device formed by using the phase shift mask of claim 8.
16. A phase shift mask for use with light at a wavelength comprising:
a mask substrate having a phase shift region, a half tone region and an unshifted phase region;

a half tone layer over said half tone region;
said phase shift region adjacent to said half tone region;
said half tone region adjacent to said unshifted phase region;
said phase shift region has about a 180 degree phase shift with respect to said unshifted phase region,
said half tone layer has a phase shift of about a 180 degrees with respect to said unshifted phase region, said half tone layer has a transmittance between about 3 and 30%.

17. The phase shift mask of claim 16 which further includes a trench in said phase shift region.
18. The phase shift mask of claim 16 wherein said unshifted phase region has about a 100 % transmittance and about a 0 degree phase shift with the incoming light.
19. The phase shift mask of claim 16 wherein said phase shift region has a phase shift such that light that at said wavelength transmitted through said phase shift region is shifted in phase by about 180 degrees relative to said light at said wavelength transmitted through said unshifted phase region.
20. The phase shift mask of claim 16 wherein said half tone region has a transmittance that balances the light intensities transmitted through said phase shift region and said unshifted region so that the light intensities are about equal.
21. A semiconductor device formed by using the phase shift mask of claim 16.
22. A phase shift mask for use with light at a wavelength comprising:
 - a) a mask substrate has a first phase shift region, a half tone region and an second phase shift region;

- b) a half tone layer over said half tone region; said half tone layer has a transmittance between about 0.1 and 98 %;
 - c) said first phase shift region and half tone layer have an about 180 degree phase shift with respect to said second phase shift region;
 - d) said first phase shift region adjacent to said half tone region;
 - e) said half tone region adjacent to said second phase shift region.
- 23. The phase shift mask of claim 22 wherein a first trench in said first phase shift region; said first phase shift region has about a 100 % transmittance.
- 24. The phase shift mask of claim 22 wherein said half tone layer has a transmittance between about 3 and 30% .
- 25. The phase shift mask of claim 22 wherein said second phase shift region has about a 100 % transmittance.
- 26. A semiconductor device or an electronics device formed by using the phase shift mask of claim 22.
- 27. A method for forming a single trench half tone phase shift mask for use with light at a wavelength comprising:
 - a) providing a substrate having a phase shift region, a half tone region and an unshifted phase region; said phase shift region adjacent to said half tone region; said half tone region adjacent to said unshifted phase region;
 - b) forming a half tone layer on said substrate in said half tone region; said half tone layer has a phase shift of about 180 degrees with said unshifted phase region, said half tone layer has a transmittance between about 3 and 30%;

- c) forming a trench in said substrate in said phase shift region; said phase shift region has an about 180 degree phase shift with said unshifted phase region.
28. The method of claim 27 wherein said trench formed to a first depth such that light that at said wavelength transmitted through said phase shift region is shifted in phase by 180 degrees relative to said light at said wavelength transmitted through said unshifted phase region.
29. A method for forming a half tone single trench phase shift mask for use with light at a wavelength comprising:
- a) providing a substrate having a phase shift region, a half tone region and an unshifted phase region and an opaque region; said phase shift region adjacent to half tone region; said half tone region adjacent to an unshifted phase region;
 - b) forming a half tone layer on said substrate;
 - c) forming an opaque layer on said half tone layer;
 - d) forming a first resist layer on said opaque layer;
 - e) removing portions of said first resist layer to form a first resist pattern over said half tone region and said opaque region;
 - f) patterning said an opaque layer on said half tone layer using the first resist pattern as a mask form a first opaque pattern and a half tone pattern over said half tone region;
 - g) removing said first resist layer;
 - h) forming a second resist layer over said opaque layer on said half tone layer and said substrate;
 - i) removing portions of said second resist layer to form a second resist pattern over said unshifted region and said opaque region and to form second resist layer openings over said phase shift region;

- j) forming a trench in said phase shift region; said trench has a depth so that said phase shift region has a phase shift of 180 degrees with said unshifted phase region;
 - k) removing said second resist pattern;
 - l) forming a third resist layer over said substrate;
 - m) removing portions of said third resist layer to form a third resist layer pattern over the opaque region and to form a third resist layer openings to expose said phase shift region, said half tone region and an unshifted phase region;
 - n) removing said opaque layer from over said half tone region layer in said half tone regions;
 - o) removing said third resist layer.
30. The method of claim 29 wherein said half tone layer has a 180 degree phase shift relative to said unshifted phase region.
31. The method of claim 29 which further includes etching said half tone pattern to control the transmission of the said half tone pattern.
32. The method of claim 29 wherein said substrate is a mask blank comprised of quartz.
33. The method of claim 29 wherein said half tone layer is comprised of a material selected from the group consisting of: molybdenum silicide, molybdenum silicon oxide, silicon nitride, and silicon oxinitride.
34. The method of claim 29 wherein said opaque layer is comprised of chrome.
35. The method of claim 29 wherein the patterning said opaque layer on said half tone layer is performed using a reactive ion etch.
36. The method of claim 29 wherein said first resist layer is negative or positive type photoresist.

37. A method for a phase shift mask for use with light at a wavelength comprising:
- a) providing a mask substrate having a first phase shift region, a half tone region and an second phase shift region;
 - b) said first phase shift region adjacent to said half tone region; said half tone region adjacent to said second phase shift region;
 - c) forming a first trench in said substrate in said first phase shift region; said phase shift region has an about 180 degree phase shift with said unshifted phase region, said first phase shift region has about a 100 % transmittance;
 - d) forming a half tone layer on said mask substrate in said half tone region; said half tone layer has a phase shift of about 180 degrees with said first phase shift region; said half tone layer has a transmittance between about 0 and 100 % ;
 - e) forming a second trench in said substrate in said second phase shift region; said second phase shift region has an about 180 degree phase shift with said first phase shift region.
38. The method of claim 37 wherein said first phase shift region creates a phase shift of about 270 degrees on incident light; said second phase shift region and said half tone layer creates a phase shift of about 90 degrees on incident light.
39. The method of claim 37 wherein said half tone layer has a transmittance between about 3 and 30 % .

40. A method for forming a half tone dual trench phase shift mask for use with light at a wavelength comprising:
- a) providing a substrate having a first phase shift region, a half tone region and a second phase shift region and an opaque region; said first phase shift region adjacent to said half tone region; said half tone region adjacent said second phase shift region;
 - b) forming a half tone layer on said substrate;
 - c) forming an opaque layer on said half tone layer;
 - d) forming a first resist layer on said opaque layer;
 - e) removing portions of said first resist layer to form a first resist pattern over said half tone region and said opaque region;
 - f) patterning said an opaque layer on said half tone layer using the first resist pattern as a mask form a first opaque pattern and a half tone pattern over said half tone region;
 - g) forming second trenches in the substrate in the second phase shift region and partial first trenches in the first phase shift regions;
 - h) removing said first resist layer;
 - i) forming a second resist layer over said opaque layer on said half tone layer and said substrate;
 - j) removing portions of said second resist layer to form a second resist pattern over said second phase shift region and said opaque region and to form second resist layer openings over said first phase shift region;
 - k) forming a first trench in said first phase shift region; said first trench has a depth so that said first phase shift region has a phase shift of about 180 degrees relative to said second phase shift region;
 - l) removing said second resist pattern;
 - m) forming a third resist layer over said substrate;

- n) removing portions of said third resist layer to form a third resist pattern over said opaque region and to form a third resist layer openings to expose said half tone pattern in said first phase shift regions, and said half tone region and an second phase shift region;
 - o) removing said opaque patterns from over said half tone pattern in said half tone regions;
 - p) removing said third resist pattern.
41. The method of claim 40 wherein said first phase shift region creates a phase shift of about 270 degrees on incident light;
said second phase shift region and said half tone layer creates a phase shift of about 90 degrees on incident light.
 42. The method of claim 40 which further includes etching said half tone pattern to control the transmission of the said half tone pattern.
 43. The method of claim 40 wherein said substrate is a mask blank comprised of quartz.
 44. The method of claim 40 wherein said half tone layer is comprised of a material selected from the group consisting of: molybdenum silicide, molybdenum silicon oxide, silicon nitride, and silicon oxynitride.
 45. The method of claim 40 wherein said opaque layer is comprised of chrome.
 46. The method of claim 40 wherein the patterning said opaque layer on said half tone layer is performed using a reactive ion etch.
 47. The method of claim 40 wherein said first resist layer is negative or positive type photoresist.
 48. A method of fabricating a semiconductor device the method comprising:

- a) providing a phase shift mask comprising:
 - (1) a mask substrate having a first phase shift section, a half tone section and a second phase section;
 - said first phase shift section adjacent to said half tone section;
 - said half tone section adjacent to said second phase section;
 - said first phase shift section and said half tone section have about a 180 degree phase shift with said second phase section;
 - said half tone section has a transmittance between about 0.1 and 98 %;
- b) transmitting radiation through portions of the phase shift mask to expose a pattern of photoresist overlying a semiconductor workpiece; and
- c) utilizing the patterned photoresist to fabricate a semiconductor device or an electronics device.

- 49. The method of claim 48 wherein said half tone section comprises a half tone region of a mask substrate and a half tone layer over said half tone region, said half tone layer has a transmittance between about 3 and 30 %.
- 50. The method of claim 48 wherein said phase shift mask further includes;
 - said first phase shift section comprises a first phase shift region of a mask substrate;
 - a first trench in said mask substrate in said first phase shift region; and
 - said second phase section has about a 0 degree phase shift.
- 51. The method of claim 48 wherein said phase shift mask includes:
 - a mask substrate having a first phase shift region, a half tone region and a second phase shift region;
 - a first trench in said first phase shift region; and
 - said first phase shift region has about a 0 degree phase shift;
 - said half tone layer has a transmittance between about 3 and 30%; and
 - a second trench in said second phase shift region.

52. The method of claim 48 wherein said phase shift mask includes:
- a mask substrate having a first phase shift region, a half tone region and a second phase shift region;
- a first trench in said mask substrate in said first phase shift region; and
- a second trench in said mask substrate in said second phase shift region; and
- said half tone layer has a transmittance between about 3 and 30%.
53. The method of claim 48 wherein said half tone region has a transmittance that about balances the light intensities transmitted through said first phase shift region and said second phase shift region so that the light intensities are about equal.
54. A method of fabricating a semiconductor device the method comprising:
- a) providing a single trench half tone phase mask comprising:
- (1) a phase shift section, a half tone section and an unshifted phase section;
 - (2) said phase shift section adjacent to said half tone section;
 - (3) said half tone section adjacent to said unshifted phase section;
 - (4) said phase shift section has an about 180 degree phase shift with said unshifted phase section;
 - (5) said half tone section has a phase shift of about 180 degrees with said unshifted phase section, said half tone section has a transmittance between about 0.1 and 98 %;

- b) transmitting radiation through portions of the phase shift mask to expose a pattern of photoresist overlying a semiconductor work piece; and
- c) utilizing the patterned photoresist to fabricate a semiconductor device or an electronics device.

55. The method of claim 54 wherein:

said first phase shift section comprised of a first phase shift region of a mask substrate;

a trench in said first phase shift region; and

said half tone section comprised of (i) a half tone region of said mask substrate and (ii) a half tone layer over said half tone region;

said second phase shift section has about a 0 degree phase shift.

56. The method of claim 54 wherein :

said first phase shift section comprised of (i) a first phase shift region of a mask substrate and (ii) a first trench in said first phase shift region;

said half tone section comprised of a half tone region of said mask substrate and a half tone layer over said half tone region; said half tone layer has a transmittance between about 3 and 30%; and

said second phase shift section has about a 0 degree phase shift.

57. The method of claim 54 wherein said half tone layer has a transmittance between about 3 and 30%.